

Product Advisory (PA)

Subject: Correction to the ISL70040SEH and ISL73040SEH datasheet for Standard Microcircuit Drawing (SMD) 5962-1723301 and 5962-1723302

Publication Date: 11/19/2018

Effective Date: 11/19/2018

Revision Description:

Initial Release

Description of Change:

This notice is to inform you of a correction (typographical error) to the wire diameter (1.5 to 1.25 mils) for the listed ISL70040SEH and ISL73040SEH products. The correction is only to the wire diameter listed in table 4 of the datasheet as shown in Appendix A.

Affected Products:

Standard microcircuit drawing	Renesas Part Number	Standard microcircuit drawing	Renesas Part Number
	ISL70040SEHL/PROTO		ISL73040SEHL/PROTO
5962R1723301VXC	ISL70040SEHVL	5962L1723302VXC	ISL73040SEHVL
5962R1723301V9A	ISL70040SEHVX	5962L1723302V9A	ISL73040SEHVX
	ISL70040SEHX/SAMPLE		ISL73040SEHX/SAMPLE

Reason for Change:

The change corrects the datasheet to reflect the actual material specifications. Details regarding the change are contained in Appendix A. The updated datasheet is available on the Renesas web site at: [ISL7x040 Datasheet](#)

Impact on fit, form, function, quality & reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

There have been no changes to the product, this is a documentation correction only. There will be no change in the external marking of the packaged products.

Qualification status: Not applicable - correction only

Sample availability: 11/19/2018

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
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Appendix A:

From:

Table 4. Layout X-Y Coordinates (Centroid of Bond Pad)

Pad Number	Pad Name	X (μm)	Y (μm)	ΔX (μm)	ΔY (μm)	Bond Wire Size (0.001")
1	V _{DD}	171.0	1968.15	120	290	1.5
2	IN	171.0	1423.85	120	135	1.5
3	INB	171.0	964.25	120	135	1.5
4	VSS	171.0	298.2	120	290	1.5
5	VSSP	1878.65	231.0	120	290	1.5
6	OUTL	1878.65	758.5	120	290	1.5
7	OUTH	1878.65	1446.95	120	290	1.5
8	VDRV	1878.65	1973.85	120	290	1.5

To:

Table 4. Layout X-Y Coordinates (Centroid of Bond Pad)

Pad Number	Pad Name	X (μm)	Y (μm)	ΔX (μm)	ΔY (μm)	Bond Wire Size (mils)
1	V _{DD}	171.0	1968.15	120	290	1.25
2	IN	171.0	1423.85	120	135	1.25
3	INB	171.0	964.25	120	135	1.25
4	VSS	171.0	298.2	120	290	1.25
5	VSSP	1878.65	231.0	120	290	1.25
6	OUTL	1878.65	758.5	120	290	1.25
7	OUTH	1878.65	1446.95	120	290	1.25
8	VDRV	1878.65	1973.85	120	290	1.25